

Title (en)  
PRODUCTION METHOD FOR MOLTEN-ALUMINUM-PLATED COPPER WIRE

Title (de)  
HERSTELLUNGSVERFAHREN FÜR KUPFERDRAHT MIT BESCHICHTUNG AUS ALUMINIUMSCHMELZE

Title (fr)  
PROCÉDÉ DE PRODUCTION DE FIL DE CUIVRE PLAQUÉ D'ALUMINIUM LIQUIDE

Publication  
**EP 3428305 A1 20190116 (EN)**

Application  
**EP 17763256 A 20170307**

Priority  
• JP 2016047841 A 20160311  
• JP 2017009037 W 20170307

Abstract (en)  
A production method for molten-aluminum-plated copper wire, the production method being characterized by use of a heating device (6) that is for heating a copper wire (2) before the copper wire (2) is immersed in a molten aluminum plating bath (1) and of a bath surface control device (7) that comprises a tube-shaped body (9), which has a through hole (9a) for passing the copper wire (2) through the inside thereof, and includes an immersion region (9b) that is for immersion in the molten aluminum plating bath (1) from an end part of one end of the tube-shaped body (9) along the long direction of the tube-shaped body (9). The production method is also characterized in that the copper wire (2) is passed, in order, through the heating device (6) and the bath surface control device (7) and immersed in the molten aluminum plating bath (1) while the immersion region (9b) of the bath surface control device (7) is immersed in the molten aluminum plating bath (1).

IPC 8 full level  
**C23C 2/38** (2006.01); **C23C 2/00** (2006.01); **C23C 2/12** (2006.01)

CPC (source: EP KR US)  
**C23C 2/00** (2013.01 - EP US); **C23C 2/0038** (2022.08 - EP KR US); **C23C 2/12** (2013.01 - EP KR US); **C23C 2/38** (2013.01 - EP KR US); **C23C 2/52** (2022.08 - KR)

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 3428305 A1 20190116**; **EP 3428305 A4 20190821**; CN 108713069 A 20181026; JP 2017166069 A 20170921; KR 20180123048 A 20181114; TW 201802264 A 20180116; US 2019136358 A1 20190509; WO 2017154916 A1 20170914

DOCDB simple family (application)  
**EP 17763256 A 20170307**; CN 201780015819 A 20170307; JP 2017009037 W 20170307; JP 2017042439 A 20170307; KR 20187027146 A 20170307; TW 106107916 A 20170310; US 201716083620 A 20170307